

(11.07.01)

AMENDMENT OF PROCEDURE  
(Amendment under the provision of Article 11)

Commissioner of Patent Office

1. Indication of International Application

PCT/JP00/06504

2. Applicant

Name CITIZEN WATCH Co., Ltd.  
Address 1-12, Tanashicho 6-chome, Nishitokyo-shi,  
Tokyo 188-8511 Japan  
Nationality Japan  
Residence Japan

3. Agent

Name (8093) OSAWA Takashi  
Address Room 818, Ikebukuro White House Bldg.,  
20-2, Higashi Ikebukuro 1-chome, Toshima-ku,  
Tokyo 170-0013 Japan

4. Object of Amendment      DESCRIPTION  
   CLAIMS

5. Content of Amendment As per attached paper

(1) In the 11th line of page 1 of DESCRIPTION,  
“respective thermoelectric semiconductors of a thermoelectric device block.” is amended to “metal or semiconductors, to which an electroless plating can not be directly applied.”

(2) After “plating bath.” in the 24th line of page 5 of DESCRIPTION,  
“, and forming an electroless plating film on the surface of the object to be plated, without the metallic film formed thereon and the metal in contact therewith. ” is added.

(3) In the 24th-25th line of page 6, in the 17th-18th line of page 7 , in the 10th-11th line of page 8 and 27th line of page 8-1st line of page 9 of DESCRIPTION,

“a plurality of bar-shaped thermoelectric semiconductors” is amended to “a plurality of thermoelectric semiconductors”

(4) Between the 1st line and the 2nd line of page 10 of DESCRIPTION, is amended to add as follows.

“And further, the present invention provides an electroless plating method comprising the steps of preparing an object to be plated, comprised of metal or semiconductors, to which an electroless plating can not be applied, and insulators, and forming a metallic film made of a metal on which an electroless plating film can be deposited on part of the surface of the object to be plated, or causing the metal to be in contact with part of the surface of the object to be plated, and dipping the object to be plated having the metallic film formed thereon or having the metal in contact therewith in an electroless plating bath, and forming an electroless plating film on the entire surface of the object to be plated, except for the insulators.

As the constituent material to which an electroless plating can not be applied,

use can be made of a metal or a semiconductor, to which an electroless plating can not be applied.

As the metal on which the electroless plating film can be deposited, use can be made of palladium, platinum or nickel.

An insulating resin is preferably used for the insulators or the insulation layers. ”

(5) Claims 1, 3, 4, 6, 7, 8 and 9 are amended as per attached papers and Claims 13, 14, 15, 16, 17, 18, 19, 20, 21 and 22 are added.

6. List of Attached Documents

(1) DESCRIPTION:	new pages 1, 5, 5/1, 6, 7, 8, 9, 10, and 10/1	1
(2) CLAIMS:	new pages 29, 29/1, 30, 30/1, 31, 32, 32/1, 33, 33/1, and 33/2	1

(Above-indicated pages and lines are based on the English translation of the original Japanese DESCRIPTION and CLAIMS.)